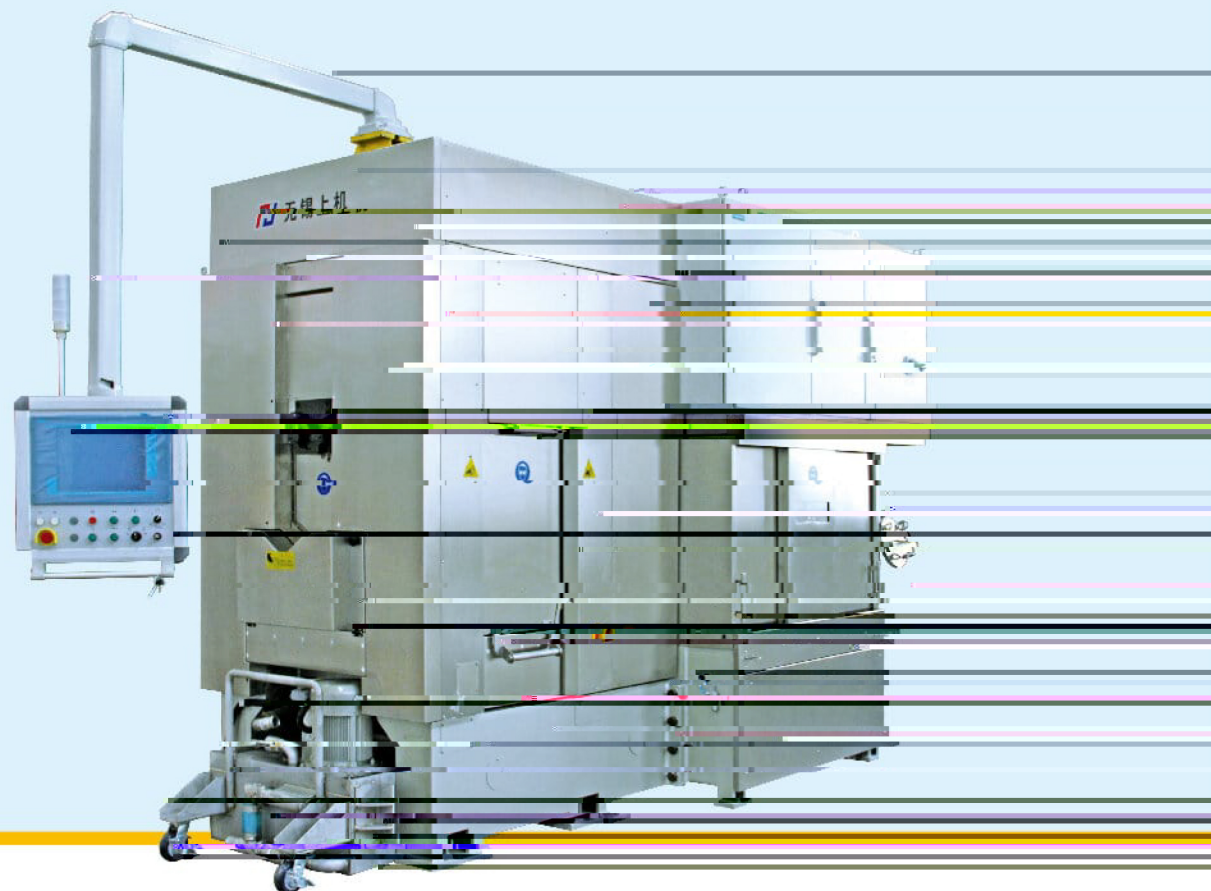


# WSK060 蓝宝石切片机

WSK060 Sapphire Slicing Machine



## 技术规格参数 Specifications and Technical Parameters

规格 Specification	6 inches (max)
长度 Length	600mm
厚度 Thickness	>0.2mm

## 主要参数 Main parameters

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheel base	440mm
导轮长度 Guide wheel length	300mm
线速度 Wire speed	500m/s (max)
进给速度 Feed rate	100mm/200mm/min
摇摆角度 Swinging angle	+12°
切割方向 Cutting direction	前进或后退切割双向切割
存储线圈 Storage wire wheel	>2000mm
水箱容量 Water tank capacity	200L

## 能源供给 Power supply

电源连接 Power connection	220/380V, 3P+N, 50/60Hz
平均功率 Average power	35KW
冷却水温 Cooling water	10~17°C

## 外形尺寸 Outline size

机床外形尺寸(长*宽*高) Equipment size (mm)	2000mm*2000mm*2000mm
机床重量 weight	≈ 12000kg

## 示意图 Sketch

### 设备用途与性能特征

- 本机床用于蓝宝石切片加工，适用于各种规格蓝宝石、硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际国内知名品牌，保证机床的稳定性。
- 采用西门子控制技术的，一体化PC机，15"触摸屏。
- 电控柜配备独立温控系统，保证各控制元件正常工作。
- 设备具备摇摆功能，双支撑摇摆单元优化了金刚石切割蓝宝石的性能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅6个滑轮），减少刚线扭曲和疲劳。

### 应用场合 Applications

- This machine is used for automatically cutting, log, hard and brittle materials, using diamond tools to cut silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components apply international and domestic outstanding brands to ensure the stability of the machine.
- Apply integrated PC or SIEMENS simotion controlling system, 15" touch screen.
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment features swinging function, and the dual support swinging function unit optimizes the performance of diamond wire-cut sapphire, shortens the cutting time, and improves the wafer quality.
- Minimal design number of pulleys (only 6 pulleys), to reduce wire distortion and fatigue.

